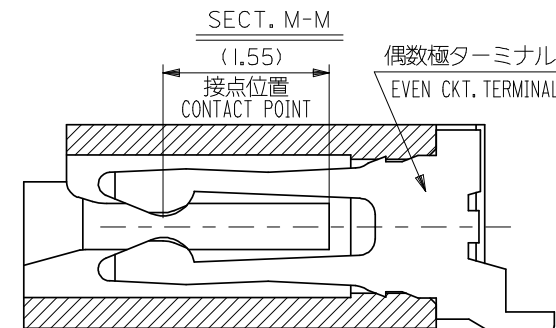
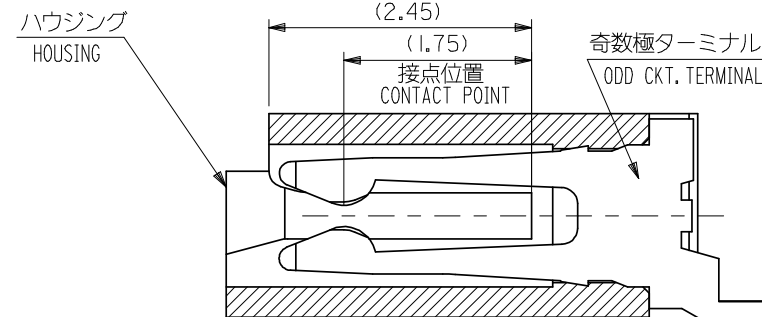
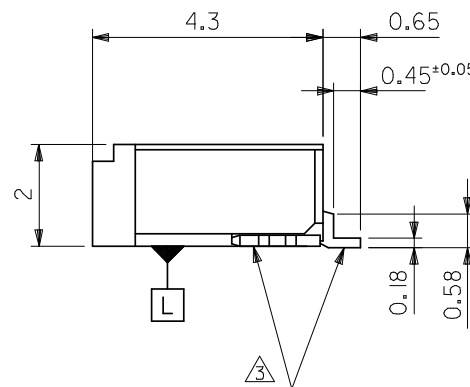
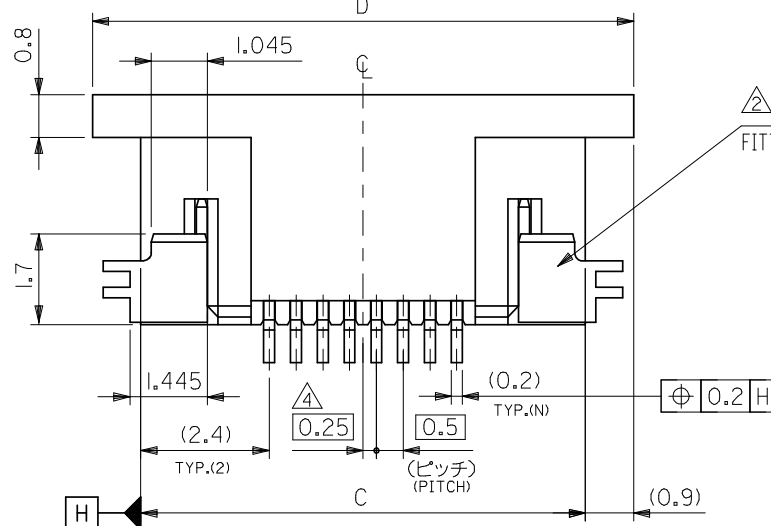
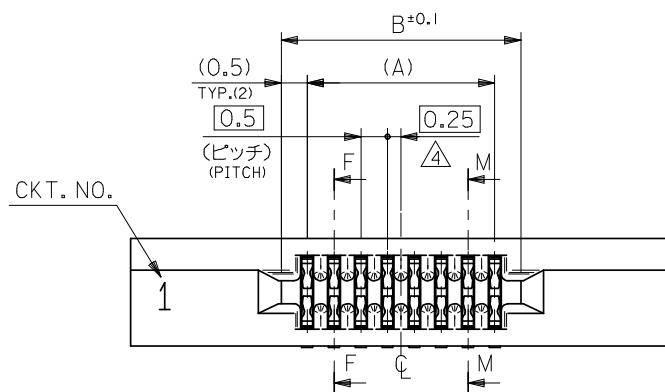
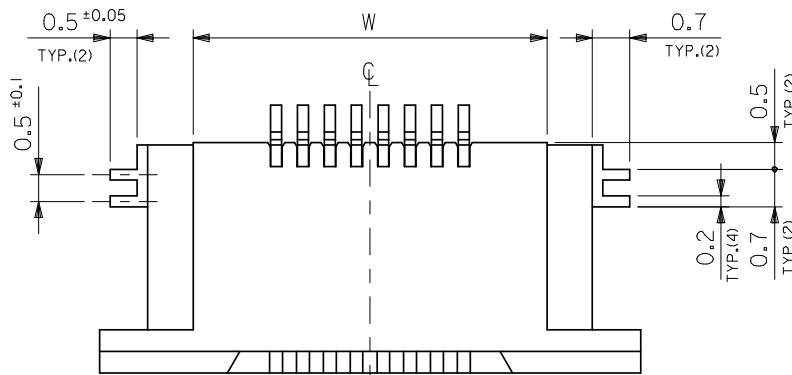




注記(NOTES)

1. 使用材料 (MATERIAL)
ターミナル (TERMINAL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫ビスマスメッキ 1. 0 マイクロメートル以上
TIN-BISMUTH I.O. MICROMETER MINIMUM
ニッケル下地 1. 0 マイクロメートル以上
NICKEL (UNDER PLATING) I.O. MICROMETER MINIMUM
ハウジング (HOUSING): 46 ナイロン (46 NYLON), UL94V-0
金具 (FITTING NAIL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫メッキ 1. 0 マイクロメートル以上
TIN I.O. MICROMETER MINIMUM
ニッケル下地 1. 0 マイクロメートル以上
NICKEL (UNDER PLATING) I.O. MICROMETER MINIMUM
2. パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB. PATTERN.)
ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L
に対し上方向 0.1 MAX.、下方向 0.15 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
UPPER DIRECTION 0.1 MAX., LOWER DIRECTION 0.15 MAX.
3. 偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
5. 本製品は 52689-***40 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE 52689-***40.

MODEL NO. 52689-***49

GENERAL TOLERANCES
(UNLESS SPECIFIED)

DIMENSION STYLE
MM ONLY

SCALE

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

10 UNDER ± 0.2

10 OVER 30 UNDER ± 0.25

30 OVER ± 0.3

ANGULAR $\pm 3^\circ$

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DRAWN BY DATE
H. KAWABATA '04/02/03

CHECKED BY DATE
K. TOJO '04/02/03

APPROVED BY DATE
M. SASAO '04/02/03

MATERIAL NO.

SEE SHEET 2

TITLE
0.5 FPC CONN NON ZIF
HSG ASSY FOR SMT(R/A)
-LEAD FREE-

MOLEX INCORPORATED

DOCUMENT NO. SD-52689-034

SHEET NO. 1 OF 2

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

F

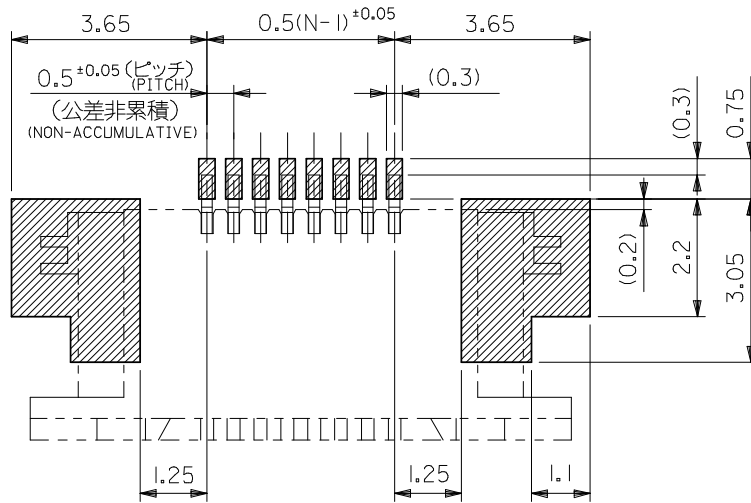
E

D

C

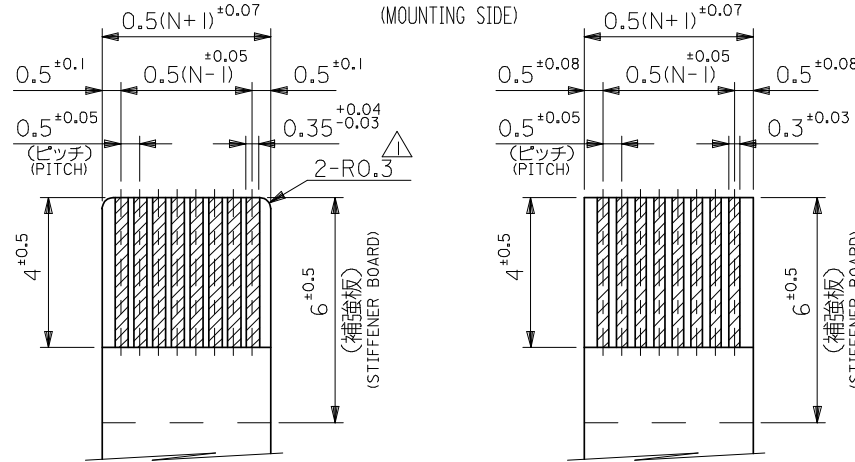
B

A



参考基板レイアウト
(マウント面)

REFERENCE P.C.BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合F P C推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

適合F F C推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

F P Cについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

- △ R0.3は、F P Cの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
17.1	20.6	18.8	15.0	14.0	-2987	-2949	29
16.6	20.1	18.3	14.5	13.5	-2887	-2849	28
16.1	19.6	17.8	14.0	13.0	-2787	-2749	27
15.6	19.1	17.3	13.5	12.5	-2687	-2649	26
15.1	18.6	16.8	13.0	12.0	-2587	-2549	25
14.6	18.1	16.3	12.5	11.5	-2487	-2449	24
14.1	17.6	15.8	12.0	11.0	-2387	-2349	23
13.6	17.1	15.3	11.5	10.5	-2287	-2249	22
13.1	16.6	14.8	11.0	10.0	-2187	-2149	21
12.6	16.1	14.3	10.5	9.5	-2087	-2049	20
12.1	15.6	13.8	10.0	9.0	-1987	-1949	19
11.6	15.1	13.3	9.5	8.5	-1887	-1849	18
11.1	14.6	12.8	9.0	8.0	-1787	-1749	17
10.6	14.1	12.3	8.5	7.5	-1687	-1649	16
10.1	13.6	11.8	8.0	7.0	-1587	-1549	15
9.6	13.1	11.3	7.5	6.5	-1487	-1449	14
9.1	12.6	10.8	7.0	6.0	-1387	-1349	13
8.6	12.1	10.3	6.5	5.5	-1287	-1249	12
8.1	11.6	9.8	6.0	5.0	-1187	-1149	11
7.6	11.1	9.3	5.5	4.5	-1087	-1049	10
7.1	10.6	8.8	5.0	4.0	-0987	-0949	9
6.6	10.1	8.3	4.5	3.5	-0887	-0849	8
6.1	9.6	7.8	4.0	3.0	-0787	-0749	7
5.6	9.1	7.3	3.5	2.5	-0687	-0649	6
5.1	8.6	6.8	3.0	2.0	52689-0587	52689-0549	5

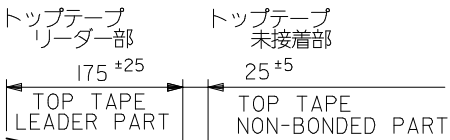
52689-***49
MODEL NO.

W D C B A
EMBOSSED TAPE
ORDER No. オーダー番号 MATERIAL NO. 極数 CKT.

REVISED EC NO: J2008-4308 DRWN:WABEI CHKD:THARUYAMA APPR:NUKITA REV B	DESCRIPTION 2008/06/27 2008/06/30 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/02/03					
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/02/03	MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-52689-034		2 OF 2		
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

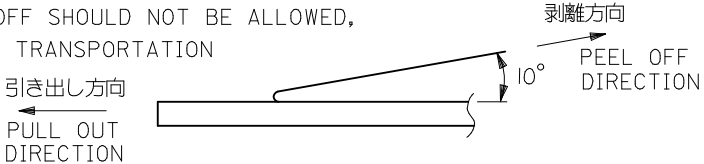
注記 NOTES

- 製品詳細寸法については図面 SD-52689-034 を参照下さい。
RE DETAILED DIMENSION,SEE SD-52689-034.
- 梱包数量：1000個／リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：（剥離方向は下図参照）
0.1～1.3N {10～130gf}
尚、本規格値は、出荷時に適用。〈但し、輸送時に剥離が発生しない事。〉

PEELING OFF FORCE OF TOP TAPE
0.1～1.3N {10～130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



- 材料
キャリアテープ：ポリプロピレン（PP）
トップテープ：PET、PE、PEF
リール：ポリスチレン（PS）＜リサイクル材を含む＞

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
＜RECYCLE MATERIAL CONTAINED＞

- 本製品は52689-**-93の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52689-**-93.

- FPCについて：
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION :
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM :POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
EC NO: J2009-2061	2009/05/20	10 UNDER	±0.2	DRAWN BY	DATE	---	METRIC	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-	
DRWN:TKON	2009/05/21	10 OVER 30 UNDER	±0.25	H.KAWABATA	2004/02/03				
CHKD:HMATSUMOTO	2009/05/21	30 OVER	±0.3	CHECKED BY	DATE			MOLEX INCORPORATED	
APPR:NUKITA	2009/05/21	ANGULAR	±3°	APPROVED BY	DATE				
REV	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	2004/02/03			SD-52689-035	
A				SEE SHEET 2,3					
				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			1 OF 3	

